

■ ELECTRICAL PERFORMANCE TEST

TEST	SPECIFICATION	TEST CONDITION
Inductance	Refer to the electrical specifications.	Measured with a LCR meter HP4284A,CH3302G
DC Resistance		Micro-ohm meter CH502A
Saturation current		DC current (A) that will cause L0 to drop approximately 20% (environment temperature of 25°C)
Heat rating current		DC current (A) that will cause an approximate μT of 40°C(environment temperature of 25°C)

■ MECHANICAL PERFORMANCE TEST

TEST	SPECIFICATION	TEST CONDITION
bending	Change from an initial value Inductance: within $\pm 10\%$	Apply pressure gradually in the direction of the arrow at a rate of about 0.5mm/s until bent depth reaches 2mm and hold for 30 sec. Boad : 40*100mm , thickness: 1mm
Adhesion strength	Change from an initial value Inductance: within $\pm 10\%$	A static load using a R0.5 pressing tool shall be applied to the body of the specimen in the direction of the arrow and shall be hold for 60 ± 5 sec.
Vibration	Change from an initial value Inductance: within $\pm 10\%$	Mesure after removing pressure. The specimen shall be subjected to a vibration of 1.5mm amplitude, sweep frequency 10~55Hz(10Hz to 55Hz to 10Hz in aperiod of one minute) for 2hr in each of 3(X,Y,Z) axes.
Mechanical shock	Change from an initial value Inductance: within $\pm 10\%$	Peak acceleration :981 m/s ² Duration of pulse :6 ms Three successive shock shall applied in the perpendicular direction of each surface of the specimen.

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solderability	New solder shall cover 90% minimum of the surface immersed.	Electrode shall be immersed in flux at room temperature and then shall be immersed in solder bath after preheat. Preheat $160 \pm 10^{\circ}\text{C}$, 90 sec Soldering $245 \pm 5^{\circ}\text{C}$, 3 ± 1 sec
Resistance to soldering heat	Change from an initial value Inductance: within $\pm 10\%$	Reflow soldering method Preheat $150 \sim 180^{\circ}\text{C}$, $90 \sim 120$ sec Peak temp. $245 \sim 250^{\circ}\text{C}$ (230°C over $30 \sim 40$ Sec.) The specimen shall be subjected to the reflow process under the above condition 2 times. Test board shall be 0.8mm thick. Base material shall be glass epoxy resin. Soldering iron method Bit temperature $230 \pm 7^{\circ}\text{C}$ Period of soldering 3sec Measurement The specimen shall be stored at standard atmospheric conditions for 1 hr in prior to the measurement.

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Low temperature	Change from an initial value Inductance: within $\pm 10\%$	The specimen shall be stored at a temperature of $-40 \pm 3^{\circ}\text{C}$ for 96hr. then it shall be stabilized under standard atmospheric conditions for 1hr before measurement. measurement shall be made within 1hr.
Dry heat	Change from an initial value Inductance: within $\pm 10\%$	The specimen shall be stored at a temperature of $85 \pm 3^{\circ}\text{C}$ for 96hr. then it shall be stabilized under standard atmospheric conditions for 1hr before measurement. measurement shall be made within 1hr.
Dump heat	Change from an initial value Inductance: within $\pm 10\%$	The specimen shall be stored at a temperature of $60 \pm 3^{\circ}\text{C}$ with relative humidity of $90 \sim 95\%$ for 96h. Then it shall be stabilized under standard atmospheric conditions for 1hr before measurement. Measurement shall be made within 1hr.
Temperature cycle	Change from an initial value Inductance: within $\pm 10\%$	The specimen shall be subjected to 10 continuous cycles of temperature change of -40°C for 30 min and 85°C for 30 min with the transit period of 2 min or less. Then it shall be stabilized under standard atmospheric conditions for 1hr before measurement. Measurement shall be made within 1hr.
Storage temperaturerange	$-40 \sim +85^{\circ}\text{C}$ * ($-40 \sim +60^{\circ}\text{C}$)	*With taping